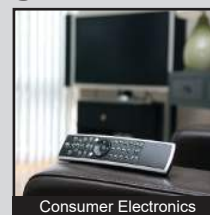
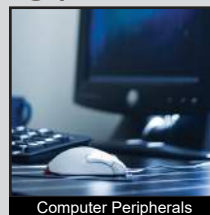
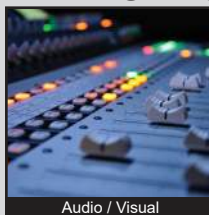


TL3275 SERIES TACT SWITCH

ANTI-VANDAL SWITCHES
DETECTOR SWITCHES
DIP SWITCHES
KEYLOCK SWITCHES
NAVIGATION SWITCHES
PUSHBUTTON SWITCHES
ROCKER SWITCHES
ROTARY SWITCHES
SLIDE SWITCHES
SNAP ACTION SWITCHES
TACTILE SWITCHES
TOGGLE SWITCHES
CAP OPTIONS



APPLICATIONS / MARKETS



RoHS

SPECIFICATIONS

Electrical Rating: 50mA, 12VDC
Contact Resistance: 500mΩ Max. (Initial)
Insulation Resistance: 100MΩ Min. at 100VDC
Dielectric Strength: 250VAC for 1 Minute
Operating Temperature: -40°C to 85°C
Operating Force: 160gf ± 50gf 100,000 cycles
Travel: 0.20mm ± 0.10mm
Function: SPST, Off-(On)
Bounce: 10msec Max.
Contact Material: Silver or Gold
Packaging: Actuator A: Tape and Reel, 1,400 pcs/reel

FEATURES & BENEFITS

- Up to 100,000 cycle life expectancy
- Tape and Reel packaging
- Surface mount design
- Multiple LED options
- Contact material options

PART NUMBER CONFIGURATOR

Series	Circuit	Actuator	Operating Force	LED Option	Contact Material
<input type="text" value="TL"/>	<input type="text" value="3275"/>	<input type="text" value="A - 3.90"/>	<input type="text" value="F160 - 160 gf ± 50 gf"/>	<input type="text" value="N"/> <input type="text" value="B"/> N - No LED B - Blue G - Green R - Red Y - Yellow W - White BG - Blue/Green Bi-color BR - Blue/Red Bi-color BY - Blue/Yellow Bi-color BW - Blue/White Bi-color GR - Green/Red Bi-color GY - Green/Yellow Bi-color GW - Green/White Bi-color RY - Red/Yellow Bi-color RW - Red/White Bi-color YW - Yellow/White Bi-color	<input type="text" value="Q"/>
					Q - Silver R - Gold

Specifications subject to change without notice 6.16.2022



E-SWITCH®

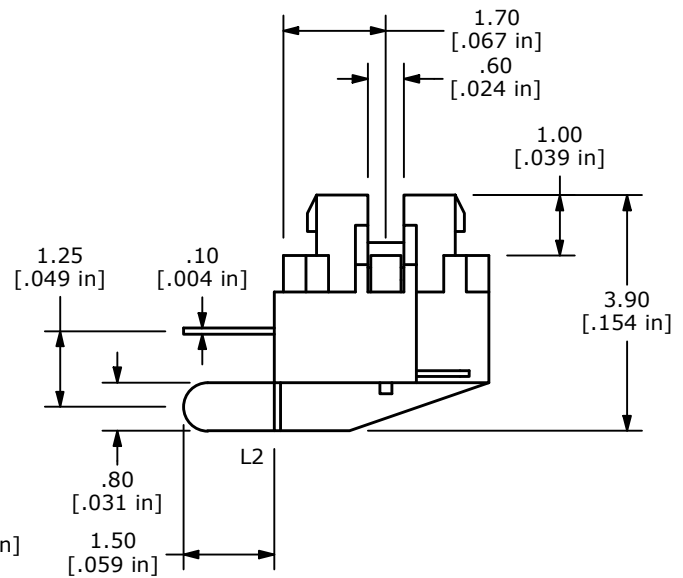
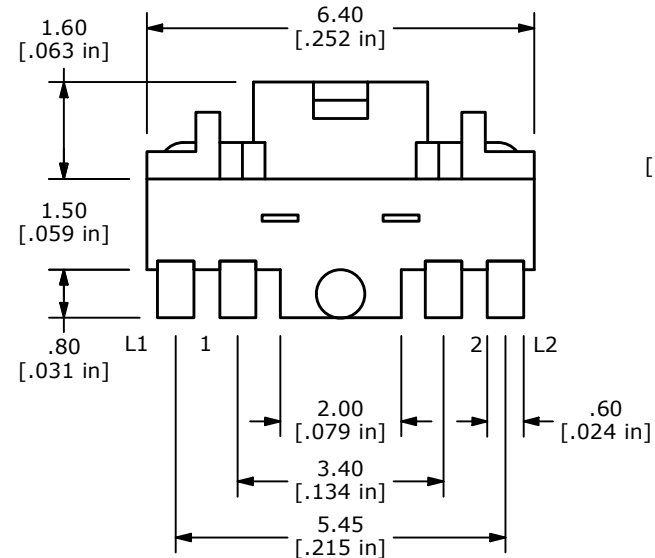
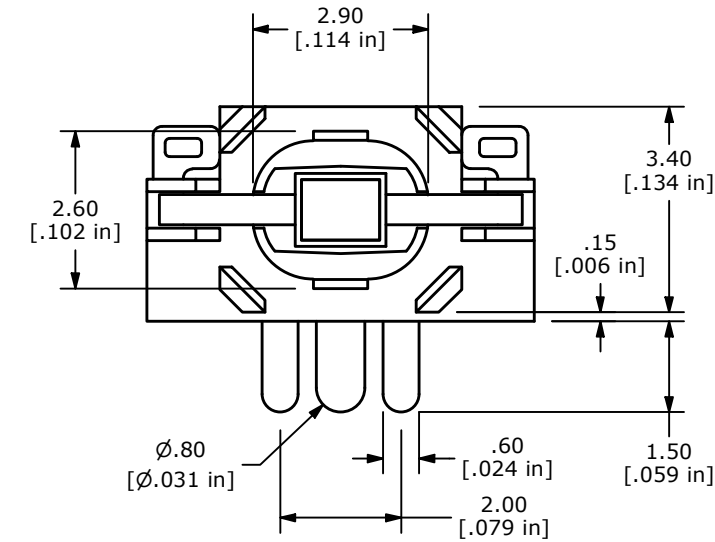
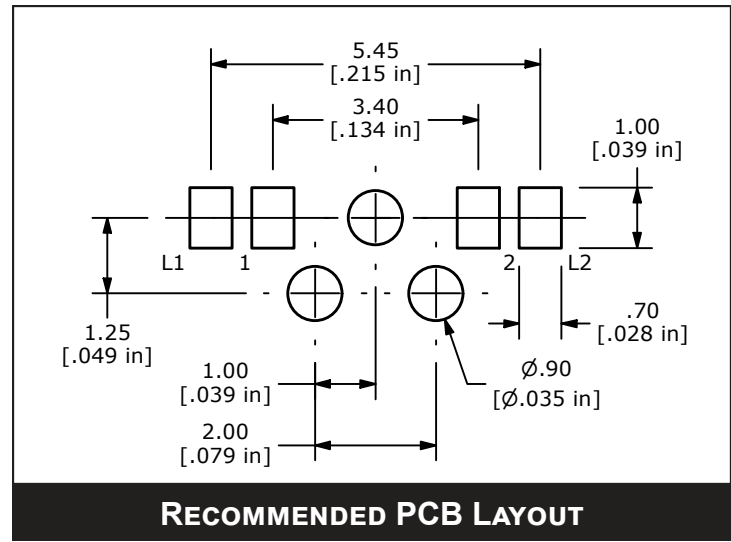
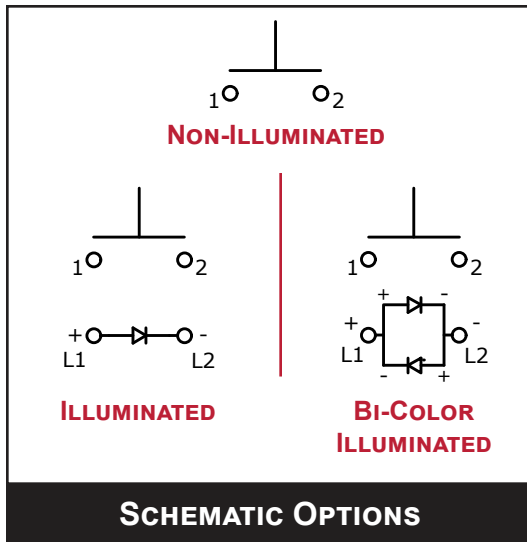
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TL3275 SERIES TACT SWITCH

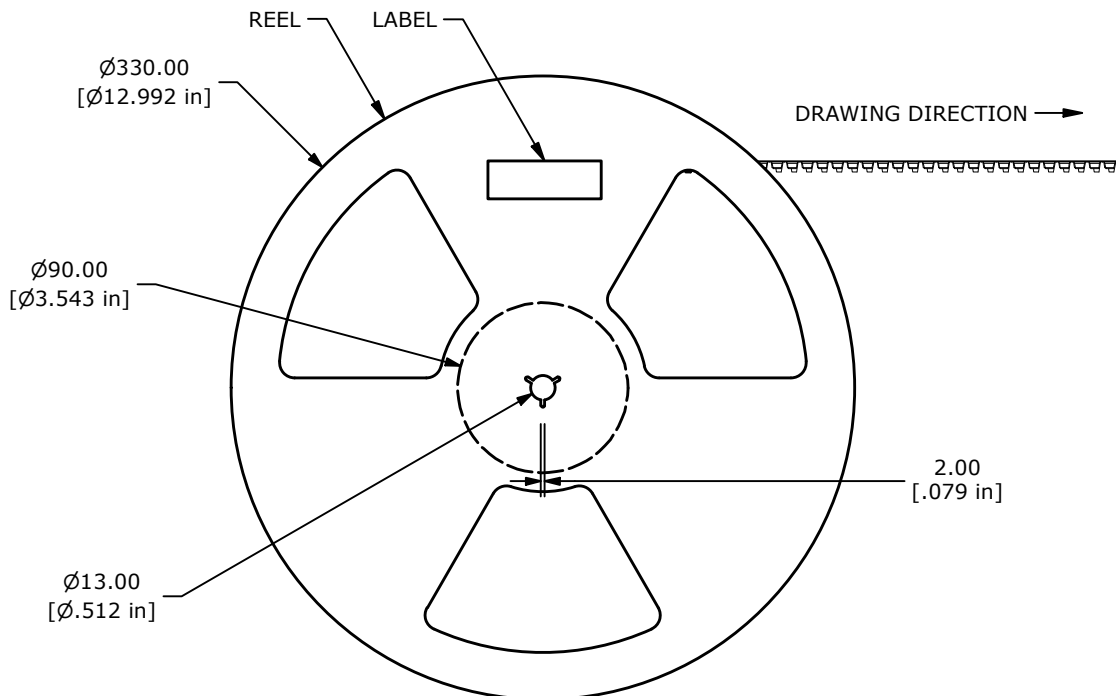
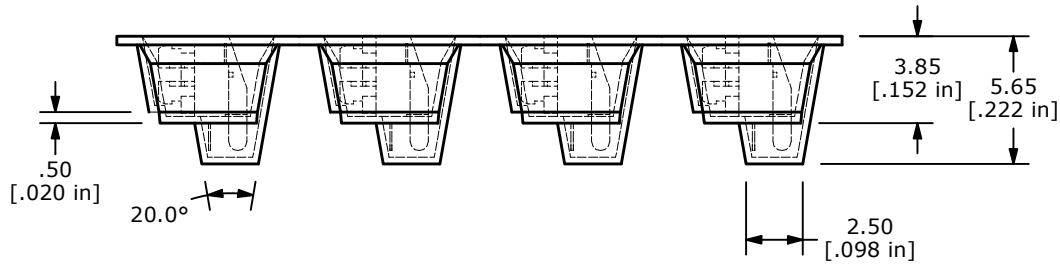
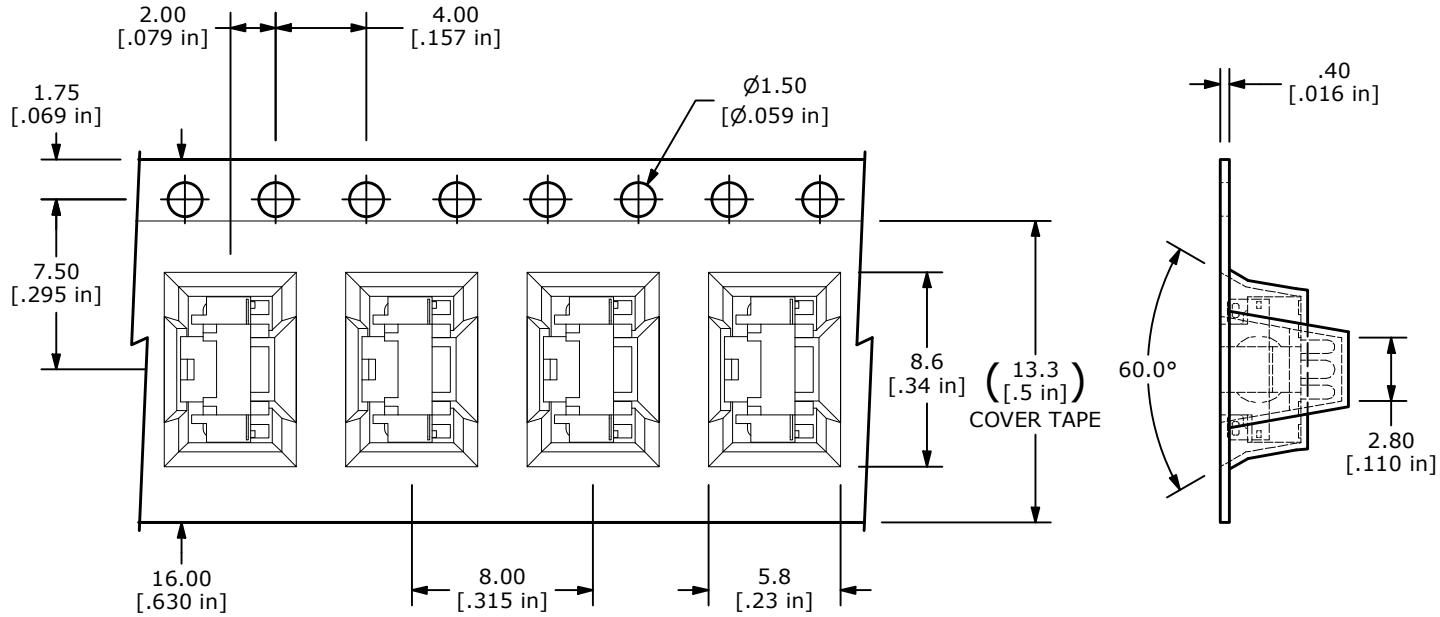
BODY DIMENSIONS



ANTI-VANDAL
DETECTOR
DIP
KEYLOCK
NAVIGATION
PUSHBUTTON
ROCKER
ROTARY
SLIDE
SNAP ACTION
TACTILE
TOGGLE
CAP
OPTIONS

TL3275 SERIES TACT SWITCH

BODY DIMENSIONS TAPE AND REEL



RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3 °C/second max.	3 °C/second max.
Preheat		
-Temperature Min (T _{smin})	100 °C	150 °C
-Temperature Max (T _{smax})	150 °C	200 °C
-Time (t _{smin} to t _{smax})	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature (T _L)	183 °C	217 °C
-Time (t _L)	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature (t _p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

